

## Features

- 3537 with integrated high quality constant current IC and RGB LED chip.
- Single line data transmission (return to zero code).
- Specific Shaping Transmit Technology - number of LED stacked is not restricted.
- Cascading Enhancement Technology - any 2 LED spacing can be up to 10 meters
- Data transfer rate of 800 kbp/s at 30 frames per second.
- RGB output port PWM control can achieve 256 gray level adjustments.

## Description

The IN-PI33TCTPRGPB is 3.5\*3.7\*1.28mm RGB LED with integrated IC. It is a SMD type LED which can be used in various applications.

## Applications

- Full color LED string light
- LED full color module
- LED guardrail tube
- LED scene lighting
- LED point light
- LED pixel screen
- LED shaped screen

## Package Outline Dimensions & Pin Configuration

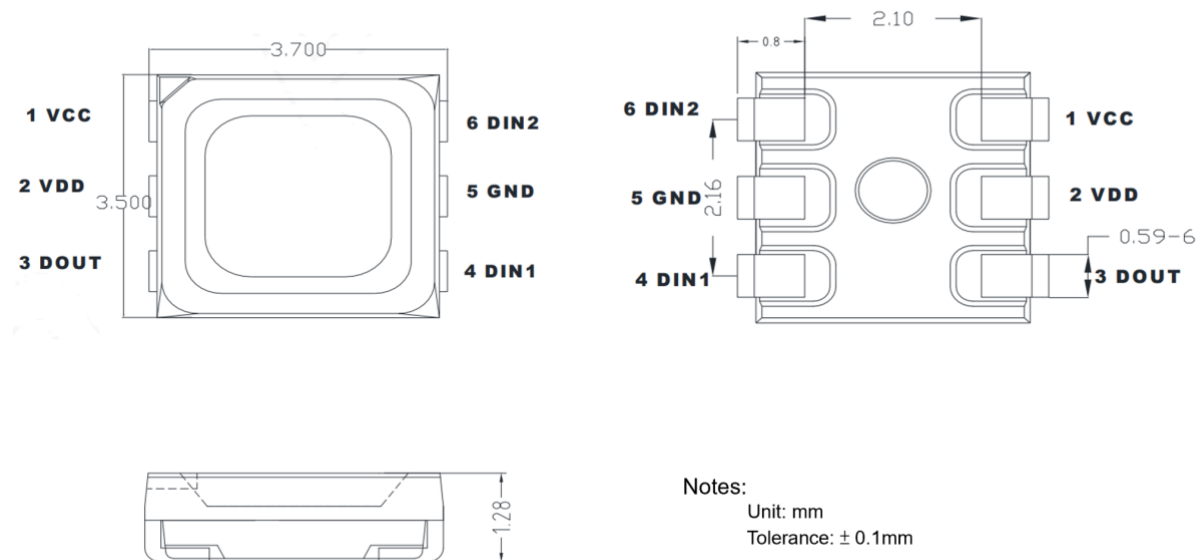


Figure 1. IN-PI33TCTPRGPB Package Outline Dimensions

### Pin Configuration

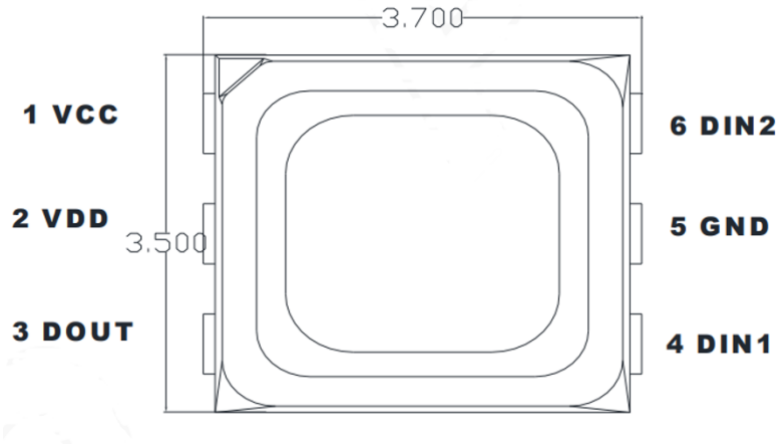


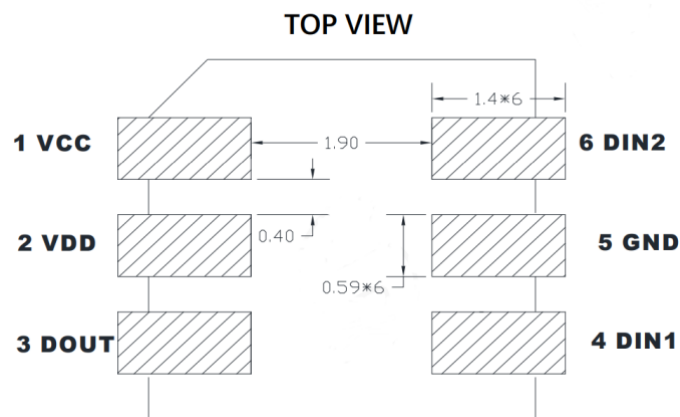
Figure 2. IN- PI33TCTPRPGPB Pin Configuration

Notes:

1. All dimensions are in millimeters.
2. Tolerance is  $\pm 0.1$ mm unless otherwise noted

| Number | Symbol | Function Description       |
|--------|--------|----------------------------|
| 1      | VCC    | Power supply LED           |
| 2      | VDD    | Power supply LED           |
| 3      | DOUT   | Control data signal output |
| 4      | DIN1   | Control data signal input  |
| 5      | GND    | Ground                     |
| 6      | DIN2   | Control data signal input  |

### Soldering Pad Size



**Absolute Maximum Rating** ( $T_a = 25^\circ\text{C}$ ,  $V_{SS}=0V$ )

| Parameter             | Symbol    | Range               | Unit             |
|-----------------------|-----------|---------------------|------------------|
| Logic supply voltage  | $V_{DD}$  | +3.7 ~ +5.5         | V                |
| Logic input voltage   | $V_{IN}$  | -0.5 ~ $V_{DD}+0.5$ | V                |
| Operating temperature | $T_{OPT}$ | -40 ~ +85           | $^\circ\text{C}$ |
| Storage temperature   | $T_{STG}$ | -40 ~ +85           | $^\circ\text{C}$ |
| ESD pressure(HBM)     | $V_{ESD}$ | 2K                  | V                |
| ESD pressure(MM)      | $V_{ESD}$ | 200                 | V                |

**LED Characteristics** ( $T_a = 25^\circ\text{C}$ )

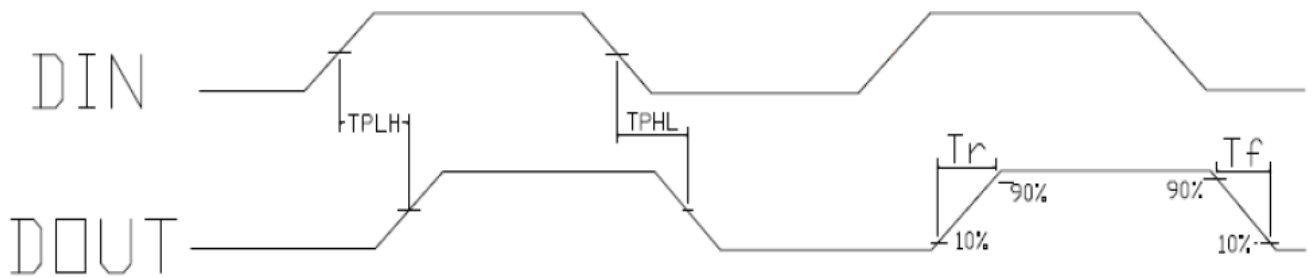
| Color | 12mA           |                      |
|-------|----------------|----------------------|
|       | Wavelength(nm) | Light Intensity(mcd) |
| Red   | 615-625        | 400-700              |
| Green | 520-530        | 1000-1500            |
| Blue  | 460-470        | 200-400              |

## Recommended Operating Ranges

| Parameter                | Symbol        | Min.    | Typ. | Max     | Unit | Test conditions |
|--------------------------|---------------|---------|------|---------|------|-----------------|
| Supply voltage           | $V_{DD}$      | 3.7     | 5.0  | 5.5     | V    | -               |
| R/G/B port pressure      | $V_{DS, MAX}$ | -       | -    | -       | V    | -               |
| High level input voltage | $V_{IH}$      | 0.7*VDD | -    |         | V    | VDD=5.0V        |
| Low level input voltage  | $V_{IL}$      | -       | -    | 0.3*VDD | V    | VDD=5.0V        |
| The frequency of PWM     | $F_{PWM}$     | -       | 4.0  | -       | KHZ  | -               |
| Static power consumption | $I_{DD}$      | -       | 0.35 | -       | mA   | -               |
| Transfer rate            | $F_{DIN}$     | -       | 800  | -       | Kbps |                 |

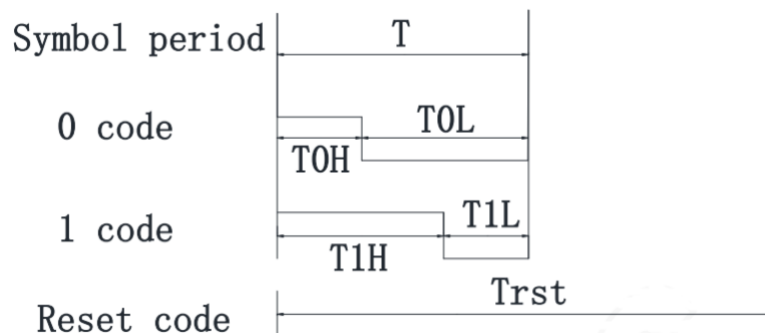
## Switching Characteristics (unless otherwise specified, $T_a=25\text{ }^{\circ}\text{C}$ )

| Parameter                      | Symbol    | Min. | Typ. | Max  | Unit | Test conditions                       |
|--------------------------------|-----------|------|------|------|------|---------------------------------------|
| The speed of data transmission | $f_{DIN}$ | -    | 800  | 1100 | KHZ  | The duty ratio of 67%<br>(data 1)     |
| DOUT transmission delay        | $T_{PLH}$ | -    | -    | 500  | ns   | DIN→DOUT                              |
|                                | $T_{PHL}$ | -    | -    | 500  | ns   |                                       |
| $I_{OUT}$ Rise/Drop Time       | $T_r$     | -    | 100  | -    | ns   | $V_{DS}=1.5$<br>$I_{OUT}=13\text{mA}$ |
|                                | $T_f$     | -    | 100  | -    | ns   |                                       |



## Timing Waveforms

### 1. Input Code



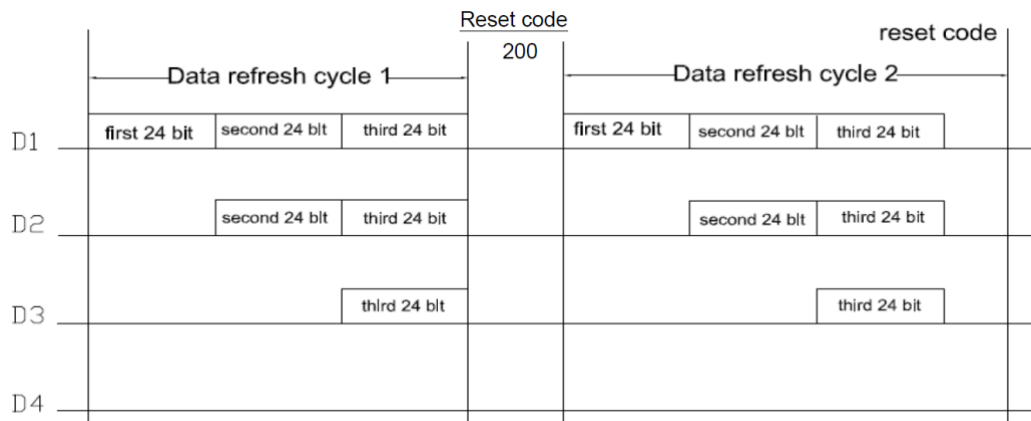
## 2. The data transmission time:

| Name | Description                | Min. | Standard Value | Max. | Unit |
|------|----------------------------|------|----------------|------|------|
| T    | Code Period                | 1.2  | -              | -    | μs   |
| T0H  | 0 code, high level time    | 0.2  | 0.32           | 0.4  | μs   |
| T0L  | 0 code, low level time     | 0.8  | -              | -    | μs   |
| T1H  | 1 code, high level time    | 0.58 | 0.64           | 1.0  | μs   |
| T1L  | 1 code, low level time     | 0.2  | -              | -    | μs   |
| Trst | Reset code, low level time | >80  | -              | -    | μs   |

### Note:

1. The protocol adopts unipolar zeroing code, and each symbol must have a low level. Each symbol in this protocol starts with a high level, and the duration of the high level determines the "0" or "1" code.
2. When writing a program, the minimum required code period is 1.2μs.
3. The high-level time of "0" and "1" codes should be within the specified range in the table above, and the low-level time of "0" and "1" codes should be less than 20μs.

## 3. Data Transfer Format



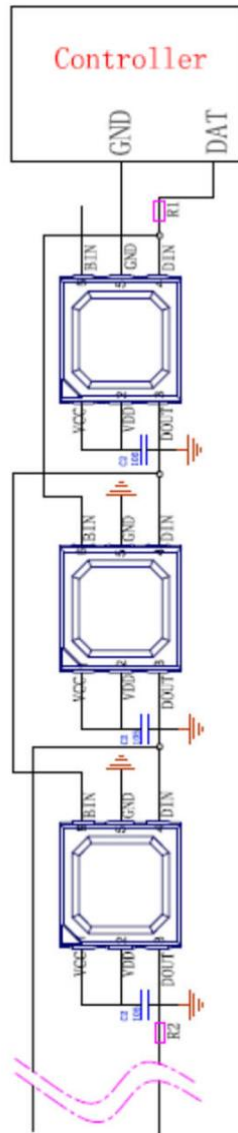
Note: D1 is the data sent by the MCU end, and D2, D3, and D4 are the data automatically shaped and forwarded by the cascaded circuit.

## 4. 24-bit data format

|    |    |    |    |    |    |    |    |    |    |    |    |
|----|----|----|----|----|----|----|----|----|----|----|----|
| G7 | G6 | G5 | G4 | G3 | G2 | G1 | G0 | R7 | R6 | R5 | R4 |
| R3 | R2 | R1 | R0 | B7 | B6 | B5 | B4 | B3 | B2 | B1 | B0 |

Note: The high bit is sent first, and the data is sent in the order of GRB. (G7 - G6 - ..... B0)

## Typical Application Circuit

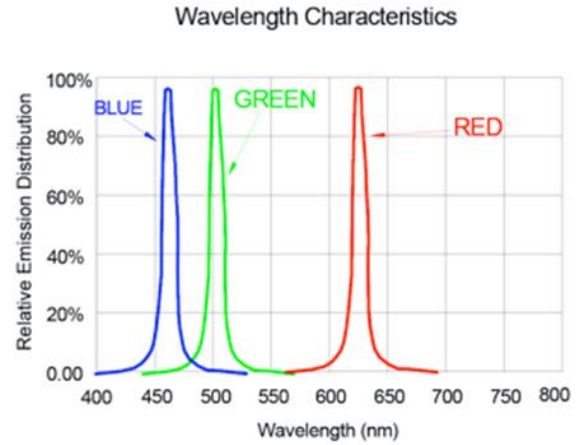
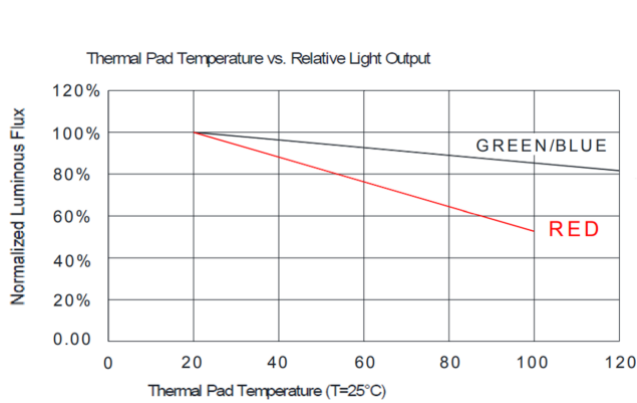


In practical application circuits, to prevent instantaneous high voltage damage to the internal signal input and output pins of the IC caused by live plugging and unplugging during testing, protective resistors should be connected in series at the signal input and output terminals. In addition, in order to ensure more stable operation between IC chips, the decoupling capacitance between each LED is essential.

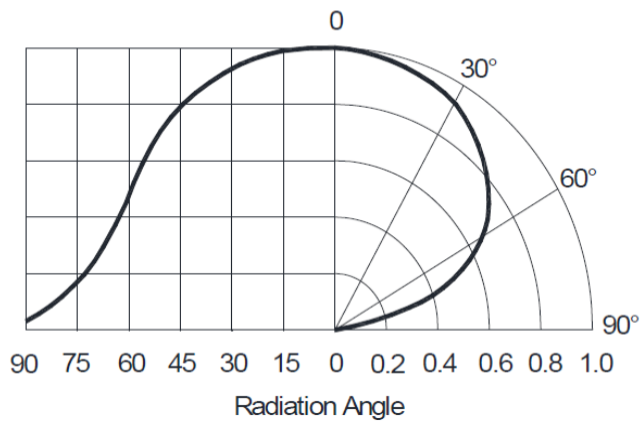
Application 1: For soft or hard light strips with short transmission distance between lamp beads, it is recommended to connect protective resistors in series at the signal input and output terminals, R1, R2, about 500 ohms.

Application 2: Used for modules or general shaped products. The transmission distance between lamp beads is long. Due to different wire materials and transmission distances, the protective resistance of the signal line connected in series at both ends will be slightly different; Based on actual usage.

## LED Performance Graph



### Typical Radiation Pattern 120°





## Ordering Information

| Product          | Emission Color | IV(mcd)   | Orderable Part Number |
|------------------|----------------|-----------|-----------------------|
| IN-PI33TCTPRPGPB | R              | 400-700   | IN-PI33TCTPRPGPB      |
|                  | G              | 1000-1500 |                       |
|                  | B              | 200-400   |                       |

## Label Specifications

|                                                                                                    |  |                                                                                                  |  |                                                                                                        |  |
|----------------------------------------------------------------------------------------------------|--|--------------------------------------------------------------------------------------------------|--|--------------------------------------------------------------------------------------------------------|--|
|                   |  |                 |  | Date: yyyy/mm/dd<br> |  |
| CUSTOMER P/N:<br> |  | INOLUX P/N:<br> |  | QTY: PCS<br>         |  |
| LOT NO:<br>       |  | QC<br>         |  |                                                                                                        |  |
| IV BIN:                                                                                            |  | COLOR BIN:                                                                                       |  | VF:                                                                                                    |  |

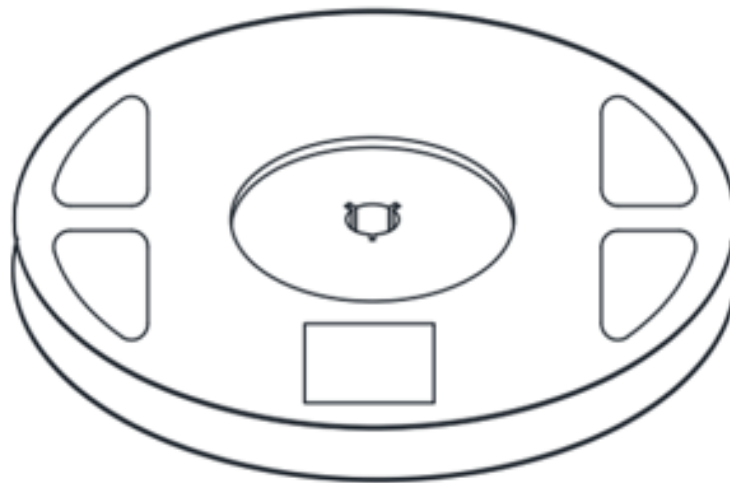
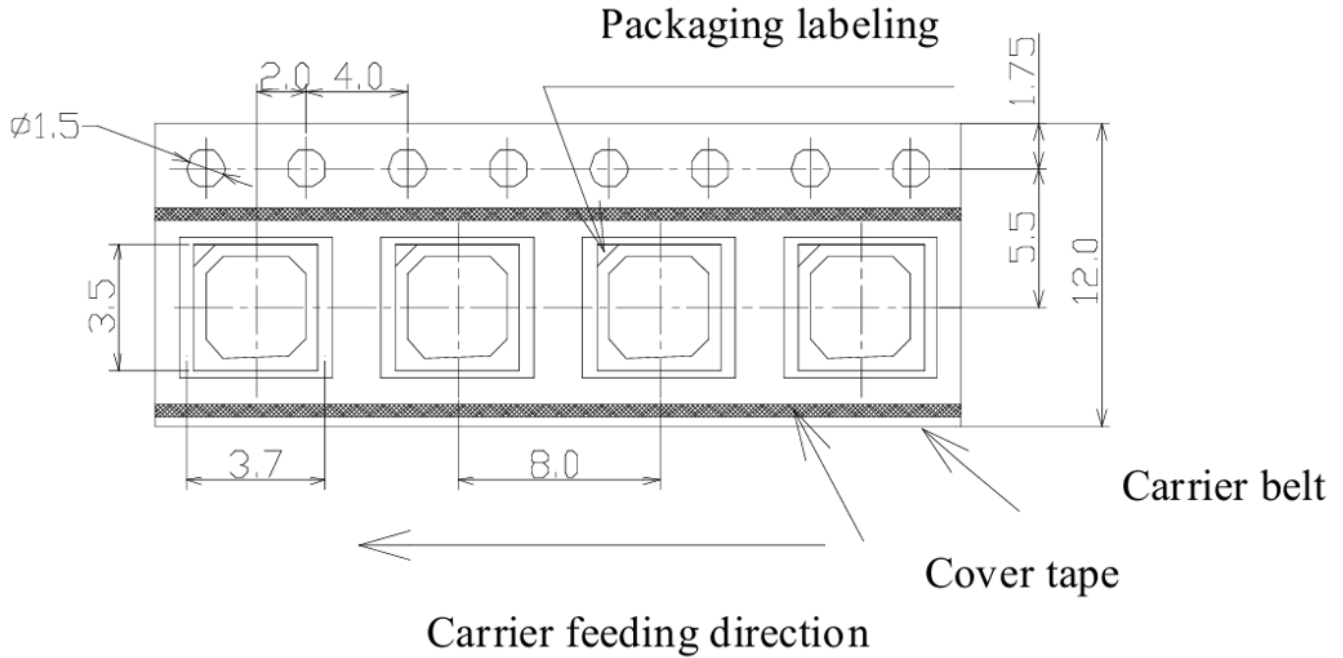
**Inolux P/N:**

| I      | N | PI                                           | - | 33                         | T        | C         | T             | P       | R          | P       | G          | P       | B          | - | X                    | X | X | X |
|--------|---|----------------------------------------------|---|----------------------------|----------|-----------|---------------|---------|------------|---------|------------|---------|------------|---|----------------------|---|---|---|
| Inolux |   | Product                                      |   | Package                    | Die Qty. | Variation | Orientation   | Current | Color      | Current | Color      | Current | Color      |   | Customized Stamp-off |   |   |   |
|        |   | PI- Single trace IC<br>PC- Clock Function IC |   | 33TC = 3.5 x 3.7 x 1.28 mm |          |           | T = Top Mount | P=12mA  | R = 620 nm | P=12mA  | G = 520 nm | P=12mA  | B = 470 nm |   |                      |   |   |   |

**Lot No.:**

|                  |                          |   |   |   |       |      |        |
|------------------|--------------------------|---|---|---|-------|------|--------|
| Z                | 2                        | 0 | 1 | 7 | 01    | 24   | 001    |
| Internal Tracker | Year (2017, 2018, .....) |   |   |   | Month | Date | Serial |

## Packaging standards



**REEL(178x12mm)**

## Precautions

Please read the following notes before using the product:

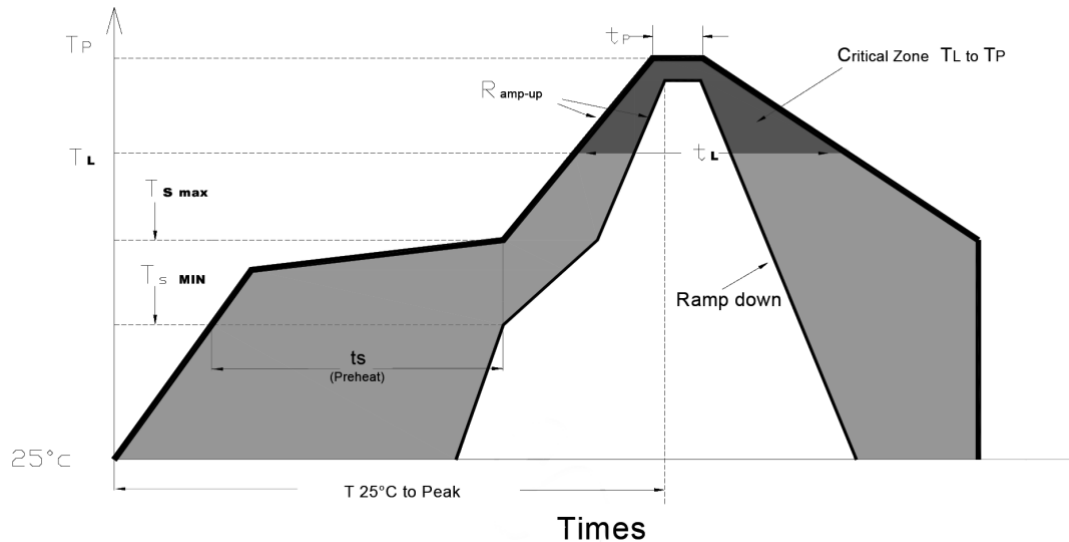
### 1. Storage

- 1.1 Do not open moisture proof bag before the products are ready to use.
- 1.2 Before opening the package, the LEDs should be kept at 30°C or less and 80%RH or less.
- 1.3 The LEDs should be used within a year.
- 1.4 After opening the package, the remaining LEDs should be kept in a resealed bag.
- 1.5 The LEDs require mandatory baking before usage. Baking treatment listed below.
- 1.6 If the moisture adsorbent material has fabled away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

\*Baking treatment: 60±5°C for 24 hours.

## 2. Soldering Condition

Recommended soldering conditions:



| Profile Feature                                      | Lead-Free Solder |
|------------------------------------------------------|------------------|
| Average Ramp-Up Rate ( $T_{S\ max}$ to $T_P$ )       | 3°C/second max.  |
| Preheat: Temperature Min ( $T_{S\ min}$ )            | 150°C            |
| Preheat: Temperature Min ( $T_{S\ max}$ )            | 200°C            |
| Preheat: Time ( $t_{s\ min}$ to $t_{s\ max}$ )       | 60-180 seconds   |
| Time Maintained Above: Temperature ( $T_L$ )         | 217 °C           |
| Time Maintained Above: Time ( $t_L$ )                | 60-150 seconds   |
| Peak/Classification Temperature ( $T_P$ )            | 240 °C           |
| Time Within 5°C of Actual Peak Temperature ( $t_p$ ) | <10 seconds      |
| Ramp-Down Rate                                       | 6°C/second max.  |
| Time 25 °C to Peak Temperature                       | <6 minutes max.  |

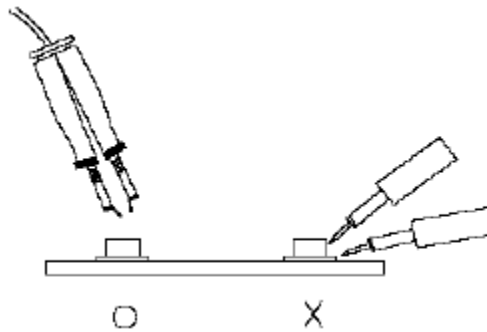
Note: Excessive soldering temperature and / or time might result in deformation of the LED lens or catastrophic failure of the LED.

### 3. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 260°C for 5 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

### 4. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



### 5. Caution in ESD

Static Electricity and surge damages the LED. It is recommended to use a wristband or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

## Revision History

| Changes since last revision | Page          | Version No. | Revision Date |
|-----------------------------|---------------|-------------|---------------|
| Initial Release             |               | 1.0         | 12-13-2018    |
| Revise precautions          | 11            | 1.1         | 07-31-2019    |
| Correct typo                | 2             | 1.2         | 02-04-2021    |
| Product Upgrade             | 1, 2, 3, 4, 9 | 1.3         | 08-22-2022    |
| Adjust the parameter        | 9             | 1.4         | 02-18-2025    |
|                             |               |             |               |
|                             |               |             |               |
|                             |               |             |               |
|                             |               |             |               |

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